

WHAT IS CLAIMED IS:

- 1 1. A chip device comprising:
 - 2 a. a die; and
 - 3 b. a leadframe including a die attach cavity, the die attach cavity
 - 4 having substantially the same thickness as the die;
 - 5 c. wherein the die is positioned within the die attach cavity and is
 - 6 attached therein.

- 1 2. The chip device of claim 1 further comprising a plurality of
- 2 dimples defined around the periphery of the leadframe that receive solder balls.

- 1 3. The chip device of claim 1 wherein the leadframe consists of a
- 2 copper based alloy.

- 1 4. The chip device of claim 3 wherein the leadframe includes a
- 2 solderable coating.

- 1 5. The chip device of claim 1 wherein the die is a bumped die.

- 1 6. A chip device comprising:
 - 2 a. a bumped die;
 - 3 b. a leadframe including a die attach cavity and a plurality of dimples
 - 4 defined around a periphery of the leadframe, the die attach cavity having substantially the
 - 5 same thickness as the die; and
 - 6 c. a plurality of solder balls placed within the dimples;
 - 7 wherein the die is positioned within the cavity and is attached
 - 8 therein.

- 1 7. The chip device of claim 6 wherein the leadframe consists of a
- 2 copper based alloy.

1 8. The chip device of claim 7 wherein the leadframe includes a
2 solderable coating.

1 9. A method of making a chip device, the method comprising:
2 providing a die;
3 providing a leadframe including a die attach cavity and a plurality of
4 dimples defined around a periphery of the leadframe, the die attach cavity having
5 substantially the same thickness as the die;
6 placing solder balls into the dimples; and
7 flipping the die into the die attach cavity and attaching it therein.

1 10. The method of claim 9 wherein the die provided is a bumped die.